

IN THE CLAIMS

Please amend the claims as follows:

1. (Currently Amended) A method of manufacturing an electric device including a bonding step wherein a semiconductor chip and a substrate are aligned so that a connection terminal on the semiconductor chip and a connection terminal on the substrate face each other, the semiconductor chip is placed onto an adhesive applied on the substrate, and heat is applied while pressing the semiconductor chip so as to connect the opposing connection terminals to each other, the bonding step including the steps of:
 - a temporary bonding step of pressing the semiconductor chip onto the adhesive in a state wherein the adhesive is heated to a first temperature no less than a reaction start temperature of the adhesive and below a reaction peak temperature of the adhesive; and
 - a permanent bonding step of heating the adhesive to a second temperature higher than the first temperature while applying pressure to the semiconductor chip, wherein when the semiconductor chip is pressed onto the adhesive in the temporary bonding step, pressure is applied to the semiconductor chip to an extent that does not cause the opposing connection terminals to be in contact with each other.
2. (Cancelled).
3. (Currently Amended) The method of manufacturing an electric device according to claim 1, wherein the second temperature is equal to, or higher than, [[a]] the reaction peak temperature of the adhesive.
4. (Original) The method of manufacturing an electric device according to claim 1, wherein the temporary bonding step comprises placing the substrate onto a first table, and heating the first table to the first temperature.

5. (Currently Amended) The method of manufacturing an electric device according to claim [[2]] 3, wherein the temporary bonding step comprises placing the substrate onto a first table, and heating the first table to the first temperature.
6. (Original) The method of manufacturing an electric device according to claim 1, wherein the temporary bonding step comprises pressing the semiconductor chip onto the adhesive after aligning the semiconductor chip and the substrate.
7. (Currently Amended) The method of manufacturing an electric device according to claim [[2]] 3, wherein the temporary bonding step comprises pressing the semiconductor chip onto the adhesive after aligning the semiconductor chip and the substrate.
8. (Currently Amended) The method of manufacturing an electric device according to claim [[1]] 4, wherein the permanent bonding step comprises transferring the substrate onto a second table different from the first table.
9. (Currently Amended) The method of manufacturing an electric device according to claim [[3]] 5, wherein the permanent bonding step comprises transferring the substrate onto a second table different from the first table.
10. (Original) The method of manufacturing an electric device according to claim 1, wherein the permanent bonding step comprises heating a heatable pressing head to the second temperature and applying pressure to the semiconductor chip with the pressing head.
11. (Currently Amended) The method of manufacturing an electric device according to claim 3, wherein the permanent bonding step comprises heating a ~~heatable~~ heatable pressing head to the second temperature and applying pressure to the semiconductor chip with the pressing head.
12. (Original) The method of manufacturing an electric device according to claim 1, wherein the permanent bonding step comprises bringing the opposing connection terminals into contact with each other, and heating the adhesive to the second temperature thereafter.

13. (Original) The method of manufacturing an electric device according to claim 3, wherein the permanent bonding step comprises bringing the opposing connection terminals into contact with each other, and heating the adhesive to the second temperature thereafter.